Clas-SiC
WAFER FAB

Dry Etch Process Engineer – Semiconductor Manufacturing

Location: Lochgelly, Fife
Company: Clas-SiC Wafer Fab Ltd
Job Type: Permanent (shift options available)
Start Date: ASAP
Salary: Competitive + attractive benefits (dependent on experience)

About Us

Clas-SiC Wafer Fab Ltd is a rapidly expanding manufacturing facility dedicated to Silicon Carbide (SiC) power semiconductor devices. Based in Lochgelly, Fife, we are scaling quickly to meet growing global demand for high-efficiency power electronics.

The Role

We are seeking a **Dry Etch Process Engineer** to join our Manufacturing Excellence Engineering Team. You will be responsible for owning, developing, and optimising plasma etch processes, ensuring exceptional quality, yield, and tool performance across Silicon Carbide device manufacturing steps.

Key Responsibilities

- Develop and optimise SiC MOSFET and diode dry-etch processes.
- Maintain stable, high-performance operation across assigned process areas.
- Identify cycle-time, capacity, and yield constraints and drive corrective actions.
- Analyse process and equipment data, report insights, and implement improvements.
- Reduce cost of ownership while improving productivity and efficiency.
- Create, update, and maintain process documentation, SOPs, and specifications.
- Collaborate with cross-functional engineering and manufacturing teams.
- Provide technical coaching and support to colleagues and technicians.
- Ensure compliance with all safety, quality, and operational standards.
- Contribute to technology roadmaps and project planning activities.

Qualifications & Experience

- Degree in Engineering or equivalent practical experience.
- Experience working in a semiconductor wafer fab environment.
- Background in developing or sustaining dry etch processes.
- Strong analytical, problem-solving, and decision-making skills.
- Excellent communication across all organisational levels.
- Competent user of Microsoft Office tools.
- Self-motivated, adaptable, and proactive.
- Hands-on experience with plasma etch tools (ICP, CCP, or similar).

- Experience optimising etch rate, selectivity, uniformity, and profile control.
- Familiarity with metrology tools such as ellipsometry, CD-SEM, profilometry, and AFM.
- Experience with SPC, DOE, FMEA, 8D, and structured root-cause analysis.
- Exposure to tool installation, qualification, and process transfer activities.
- Experience mentoring junior engineers or technicians in a fab setting.

Working Hours

40 hours per week (shift patterns available)